

**Date:** May 2026  
**Rev:** VIII  
**No. of Components:** Single  
**Mix Ratio by Weight:** N/A  
**Specific Gravity:** 2.94  
**Pot Life:** 2 - 3 Days  
**Shelf Life- Syringe:** One year at -40°C

**Recommended Cure: 150°C / 1 Hour**

Minimum Alternative Cure(s):  
*May not achieve performance properties listed below*  
 175°C / 45 Seconds  
 150°C / 5 Minutes  
 120°C / 15 Minutes  
 100°C / 45 Minutes

**NOTES:**

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

**Product Description:** EPO-TEK® H20S-D is a single component, silver-filled epoxy with a smooth, thixotropic consistency. It is a version of EPO-TEK® H20S designed primarily for enhanced dispensing.

**Typical Properties:** Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.  
 Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Silver		
* Consistency:	Smooth thixotropic paste		
* Viscosity (23°C) @ 100 rpm:	800 - 2,400	cPs	
Thixotropic Index:	4.8		
* Glass Transition Temp:	≥ 70	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	48	x 10 <sup>-6</sup> in/in°C
	Above Tg:	280	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:	60		
Lap Shear @ 23°C:	1,252	psi	
Die Shear @ 23°C:	≥ 10	Kg	3,556 psi
Degradation Temp:	404	°C	
Weight Loss:			
	@ 200°C:	0.05	%
	@ 250°C:	0.16	%
	@ 300°C:	0.82	%
Suggested Operating Temperature:	< 300 °C (Intermittent)		
Storage Modulus:	1,001,590	psi	
Ion Content:	Cl <sup>-</sup> :	163 ppm	Na <sup>+</sup> : 0 ppm
	NH <sub>4</sub> <sup>+</sup> :	282 ppm	K <sup>+</sup> : 4 ppm
* Particle Size:	≤ 20 microns		

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	2.2	W/mK
* Volume Resistivity @ 23°C:	≤ 0.0005	Ohm-cm

**Epoxyes and Adhesives for Demanding Applications™**

**SELLER MAKES NO OTHER WARRANTY OR GUARANTEE OF ANY KIND REGARDING FITNESS OF THE PRODUCT FOR A PARTICULAR PURPOSE. BUYER ASSUMES FULL RESPONSIBILITY FOR QUALITY CONTROL, TESTING AND DETERMINATION OF SUITABILITY OF PRODUCT FOR ITS INTENDED APPLICATION OR USE.**

**EPOXY TECHNOLOGY, INC.**

**14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782**

[www.epotek.com](http://www.epotek.com)

**EPO-TEK® H20S-D Advantages & Suggested Application Notes:**

- Especially recommended for use in high speed epoxy chip bonding systems where fast cures are highly desirable.
- Suggested for JEDEC Level III and II plastic IC packaging.
- The low temperature cure makes it ideal for flex circuitry and other low stress applications.
- It is used extensively for bonding quartz crystal oscillators and other stress sensitive chips.
- Used for die and SMD bonding inside hybrid/hermetic packages such as DIP and TO-Cans; also EMI/Rf shielding of micro-electronics.
- Ideal for making ITO electrical contacts in LCD packaging; and suggested for LED die-attach.

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